

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number:

0739433200

Status:

Active

Overview:

[hdm](#)

Description:

2.00mm (.079") Pitch HDM® Board-to-Board Backplane Header, Vertical, Solder Tail, Closed End, 144 Circuits

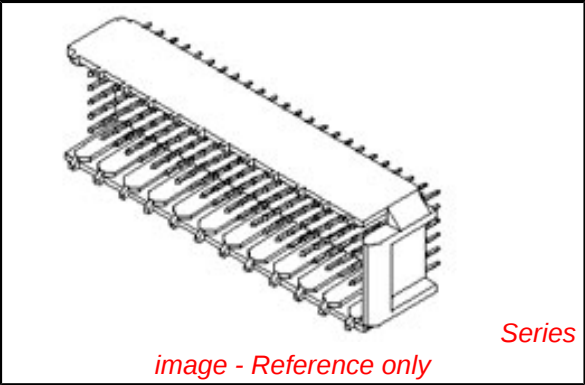
Documents:

[3D Model](#)

[Drawing \(PDF\)](#)

[RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification	
CSA	LR19980
UL	E29179
General	
Product Family	Backplane Connectors
Series	73943
Application	Backplane
Comments	Solder Tail
Component Type	PCB Header
Overview	hdm
Product Name	HDM®
Style	N/A
Physical	
Circuits (Loaded)	144
Circuits (maximum)	144
Color - Resin	Black, Natural
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Number of Columns	24
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length (in)	0.098 In
PC Tail Length (mm)	2.50 mm
PCB Retention	None
PCB Thickness Recommended (in)	0.098 In
PCB Thickness Recommended (mm)	2.50 mm
Packaging Type	Tube
Pitch - Mating Interface (in)	0.079 In
Pitch - Mating Interface (mm)	2.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.75
Plating min: Termination (µin)	100
Plating min: Termination (µm)	2.5
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55°C to +105°C



EU RoHS

ELV and RoHS

Compliant

REACH SVHC

Contains SVHC: No

Halogen-Free

Status

Not Reviewed

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com

For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

[73943Series](#)

Mates With

[73632](#) HDM PLUS® Board-to-Board Daughtercard Receptacle. [73780](#) HDM® Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description	Product #
HDM® Backplane	0621001400
Insertion Signal	
Contact Tool	
Extraction Tool	0621001000

Termination Interface: Style	Through Hole
Electrical	
Current - Maximum per Contact	1A
Data Rate	1.0 Gbps
Voltage - Maximum	250V AC
Solder Process Data	
Duration at Max. Process Temperature (seconds)	40
Lead-free Process Capability	SMC & Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	3
Process Temperature max. C	260
Material Info	
Reference - Drawing Numbers	
Packaging Specification	PK-70873-0818
Sales Drawing	SD-73943-001
HDM and High Density Metric are trademarks of Amphenol Corporation	

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NOTES:

1. MATERIALS: HOUSING--LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, UL94V-0, COLOR: BLACK.
TERMINAL: PHOSPHOR BRONZE.
2. FINISH: 0.75 MICROMETERS MINIMUM SELECTIVE GOLD (Au) IN MATING AREA
2.50 MICROMETERS MINIMUM SELECTIVE TIN (Sn) IN TAIL AREA
NICKEL (Ni) UNDERPLATE OVERALL.
3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73670-9999.
4. FOR MIXED CONTACT MATING LENGTHS, CONSULT FACTORY FOR AVAILABILITY.
5. PACKAGE PER PK-70873-0818.
6. PARTS MARKED WITH PART NUMBER AND DATE CODE, ON EITHER SIDE, APPROXIMATELY WHERE SHOWN.



SEE NOTE 6


 PCB LAYOUT: COMPONENT SIDE
 RECOMMENDED PCB THICKNESS: 2.50 MIN

2	A
1	G
SHT	REV

MODIFY FINISH NOTE
EC NO: UCP2007-2259
IDRW:MSI:BARRA 2007/03/13
CHKD:BBARKER 2007/03/21
APPR:SMILLER 2007/03/22
REV

QUALITY SYMBOLS
▽=0
▽=0
DESCRIPTION
REV

GENERAL TOLERANCES (UNLESS SPECIFIED)		
	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.05	± ---
1 PLACE	± 0.10	± ---
ANGULAR ± 1/2°		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		

DIMENSION STYLE	MM ONLY
DRAWN BY	DATE
JB INGHAM	1998/01/13
CHECKED BY	DATE
SREED	1998/01/13
APPROVED BY	DATE
CBIXLER	1998/01/13
MATERIAL NO.	
SEE CHART	
SIZE	B

SCALE	2:1
DESIGN UNITS	METRIC
THIRD ANGLE PROJECTION	
TITLE	SALES ASSY HDM BACKPLANE END WALL OPTION SOLDER TAIL VERSION
MOLEX	MOLEX INCORPORATED
DOCUMENT NO.	SD-73943-001
SHEET NO.	1 OF 2

MATERIAL NUMBER ASSIGNMENT

73943-* * 0 0

NUMBER	CIRCUIT SIZE	DIM "A"	DIM "B"	DIM "H"
0	72	27.6	22.00	2.0
1	144	51.6	46.00	2.0
2	72	27.6	22.00	2.5
3	144	51.6	46.00	2.5
4	72	27.6	22.00	3.0
5	144	51.6	46.00	3.0
6	72	27.6	22.00	3.5
7	144	51.6	46.00	3.5

NUMBER	DIM "M"
0	5.0
1	5.5
2	6.0

SEE SHEET 1 EC NO. U81577 DRWN:JBINGHAM 98/02/03 CHK: REED 98/02/03 APPR:CBIXLER 98/02/03 A	DESCRIPTION REV	QUALITY SYMBOLS MAJOR CRITICAL	GENERAL TOLERANCES: (UNLESS SPECIFIED)		SCALE NO:NE	DESIGN UNITS ☒ mm ☐ INCH	THIRD ANGLE PROJECTION	DIMENSIONS: ☐ mm ☐ INCH ☒ mm ONLY	SHT	REV		
					DRAWN BY & DATE JBINGHAM 98/01/13	TITLE: SALES ASS'Y, HDM BACKPLANE END WALL OPTION SOLDER TAIL VERSION MOLEX INCORPORATED			MATERIAL NO. SEE CHART	DRAWING NO. SD-73943-001	SHEET NO. 2	
					CHECKED BY & DATE SREED 98/01/13							
					APPROVED BY & DATE CBIXLER 98/01/13							
		ANGULAR: ± °		CAD FILENAME S73943X2.DGN								
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.							

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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